

Product / Package Information

Package	SOIC_N
Body Size	150 mils
Lead Count	16
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	8.21 E-02	86.2	862000	52.73	527271
Thermosets	Epoxy resin	Proprietary	7.15 E-03	7.5	75000	4.59	45876
Thermosets	Phenol Novolac	9003-35-4	3.81 E-03	4	40000	2.45	24467
Other inorganic materials	Antimony Trioxide	1309-64-4	1.43 E-03	1.5	15000	0.92	9175
Thermosets	Brominated Resin	40039-93-8	4.77 E-04	0.5	5000	0.31	3058
Other inorganic materials	Carbon Black	1333-86-4	2.86 E-04	0.3	3000	0.18	1835
Subtotal			9.53 E-02	100	1000000	61.17	611683

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.06 E-02	97.57	975706	32.48	324753
Copper & its alloys	Iron	7439-89-6	1.18 E-03	2.28	22789	0.76	7585
Copper & its alloys	Zinc	7440-66-6	6.55 E-05	0.13	1263	0.04	420
Copper & its alloys	Phosphorus	7723-14-0	1.26 E-05	0.02	242	0.01	81
Subtotal			5.19 E-02	100.00	1000000	33.28	332839

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.24 E-04	100.0	1000000	0.34	3362

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.92 E-03	100.0	1000000	1.87	18740

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.10 E-04	99.99	1000000	0.33	3273

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.57 E-03	100.0	1000000	2.29	22914

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	8.96 E-04	80	800000	0.58	5751
Thermosets	Epoxy Resin	Proprietary	1.68 E-04	15	150000	0.11	1078
Others	Curing agent & hardener	Proprietary	5.60 E-05	5	50000	0.04	359
Subtotal			1.12 E-03	100	1000000	0.72	7189

Package Totals	Weight (g)	Percentage (%)	PPM
	1.56 E-01	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary



Product / Package Information	
Package	SOIC_N
Body Size	150 mils
Lead Count	16
Terminal Finish	NiPdAu

Environmental Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	9.19 E-02	87.7	877000	56.56	565582
Thermosets	Epoxy Resin	Proprietary	5.24 E-03	5.0	50000	3.22	32245
Thermosets	Phenol Resin	Proprietary	5.24 E-03	5.0	50000	3.22	32245
Thermosets	Epoxy Cresol Novolac	29690-82-2	2.10 E-03	2.0	20000	1.29	12898
Other inorganic materials	Carbon Black	1333-86-3	3.14 E-04	0.3	3000	0.19	1935
Subtotal			1.05 E-01	100.0	1000000	64	644905

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.25 E-02	97.5	975000	32.28	322760
Copper & its alloys	Iron	7439-89-6	1.26 E-03	2.35	23500	0.78	7779
Copper & its alloys	Zinc	7440-66-6	6.46 E-05	0.12	1200	0.04	397
Copper & its alloys	Phosphorus	7723-14-0	1.61 E-05	0.03	300	0.01	99
Subtotal			5.38 E-02	100	1000000	33	331036

Internal/External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	1.25 E-03	97.27	972697	0.77	7721
Precious metals	Palladium	7440-05-3	2.92 E-05	2.26	22621	0.02	180
Precious metals	Gold	7440-57-5	6.04 E-06	0.47	4683	0.00	37
Subtotal			1.29 E-03	100.00	1000000	0.79	7937

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.10 E-04	99.99	1000000	0.19	1907

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.63 E-03	100	1000000	1.00	10030

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.28 E-04	77.71	777100	0.33	3251
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-96-5	2.11 E-05	3.11	31100	0.01	130
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	2.11 E-05	3.11	31100	0.01	130
Other organic materials	Butyrolactone, gamma-	96-48-0	2.11 E-05	3.11	31100	0.01	130
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	2.11 E-05	3.11	31100	0.01	130
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	2.11 E-05	3.11	31100	0.01	130
Other organic materials	Organosilane	TS ref# 10001	2.11 E-05	3.11	31100	0.01	130
Other inorganic materials	Copper(II) oxide	1317-38-0	2.11 E-05	3.11	31100	0.01	130
Other organic materials	Epoxy resin modifier	TS ref# 10038	3.54 E-06	0.52	5200	0.002	22
Subtotal			6.80 E-04	100	1000000	0.42	4184

Package Totals	Weight (g)	Percentage (%)	PPM
	1.63 E-01	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary



Product / Package Information

Package	SOIC_N
Body Size	150 mils
Lead Count	16
Terminal Finish	SnPb

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	8.21 E-02	86.2	862000	52.73	527271
Thermosets	Epoxy resin	Proprietary	7.15 E-03	7.5	75000	4.59	45876
Thermosets	Phenol Novolac	9003-35-4	3.81 E-03	4	40000	2.45	24467
Other inorganic materials	Antimony Trioxide	1309-64-4	1.43 E-03	1.5	15000	0.92	9175
Thermosets	Brominated Resin	40039-93-8	4.77 E-04	0.5	5000	0.31	3058
Other inorganic materials	Carbon Black	1333-86-4	2.86 E-04	0.3	3000	0.18	1835
Subtotal			9.53 E-02	100	1000000	61.17	611683

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.06 E-02	97.57	975706	32.48	324753
Copper & its alloys	Iron	7439-89-6	1.18 E-03	2.28	22789	0.76	7585
Copper & its alloys	Zinc	7440-66-6	6.55 E-05	0.13	1263	0.04	420
Copper & its alloys	Phosphorus	7723-14-0	1.26 E-05	0.02	242	0.01	81
Subtotal			5.19 E-02	100.00	1000000	33.28	332839

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.24 E-04	100.0	1000000	0.34	3362

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.48 E-03	85.0	850000	1.59	15929
Tin & its alloys	Lead	7439-92-1	4.38 E-04	15.0	150000	0.28	2811
Subtotal			2.92 E-03	100.0	1000000	1.87	18740

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.10 E-04	99.99	1000000	0.33	3273

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.57 E-03	100.0	1000000	2.29	22914

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	8.96 E-04	80	800000	0.58	5751
Thermosets	Epoxy Resin	Proprietary	1.68 E-04	15	150000	0.11	1078
Others	Curing agent & hardener	Proprietary	5.60 E-05	5	50000	0.04	359
Subtotal			1.12 E-03	100	1000000	0.72	7189

Package Totals	Weight (g)	Percentage (%)	PPM
	1.56 E-01	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability any inaccuracy of such information.



ADI Proprietary